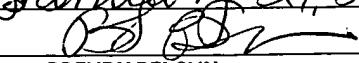


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BRENDRY BELONY  
Any fee due as a result of this paper, not covered by an enclosed  
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Attorney Docket No.: NECF 18.363A

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Inventor : Hirokazu HONDA  
Serial No. :  
Filed : January 21, 2004  
Title : FLIP-CHIP TYPE SEMICONDUCTOR DEVICE AND  
METHOD OF MANUFACTURING THE SAME  
Examiner :  
Group Art Unit :  
Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

**PRELIMINARY AMENDMENT**

SIR:

Prior to examination on the merits, please amend the above-captioned application as follows: